

Title (en)

INTEGRATED PHOTSENSITIVE STRUCTURES AND PASSIVATION METHOD

Title (de)

INTEGRIERTE FOTOEMPFLINDLICHE STRUKTUREN UND PASSIVIERUNGSVERFAHREN

Title (fr)

STRUCTURES PHOTOSENSIBLES INTEGREES ET PROCEDE DE PASSIVATION

Publication

EP 1535339 A2 20050601 (DE)

Application

EP 03750301 A 20030829

Priority

- DE 0302873 W 20030829
- DE 10239643 A 20020829
- DE 10239642 A 20020829

Abstract (en)

[origin: WO2004021453A2] The invention relates to an integrated circuit according to CMOS/BiCMOS technology and a method for producing the same. At least one integrated, photosensitive component and one electrical shield are provided, a second layer system (2; 3, 4) being applied to a photosensitive area (1) of the circuit (A) to be protected against an (unwanted) electrical coupling, said second layer system comprising a last layer (3) of a first sealing passivation layer system (5) according to the process, and a subsequent, transparent, electroconductive layer (4). Said layers have adjusted individual thicknesses (d3, d4) in order to obtain an optical thickness of the second layer system (2) having maximum transparency with a reduced thickness tolerance influence.

IPC 1-7

H01L 27/146; **H01L 31/0216**

IPC 8 full level

H01L 27/146 (2006.01); **H01L 31/00** (2006.01); **H01L 31/0216** (2006.01)

CPC (source: EP)

H01L 31/02162 (2013.01)

Citation (search report)

See references of WO 2004021452A2

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE SI SK TR

DOCDB simple family (publication)

WO 2004021453 A2 20040311; **WO 2004021453 A3 20040610**; AT E422712 T1 20090215; AU 2003269691 A1 20040319; AU 2003269691 A8 20040319; AU 2003271515 A1 20040319; AU 2003271515 A8 20040319; DE 10393329 D2 20050616; DE 10393435 D2 20050616; DE 50311172 D1 20090326; EP 1532691 A2 20050525; EP 1532691 B1 20090211; EP 1535339 A2 20050601

DOCDB simple family (application)

DE 0302874 W 20030829; AT 03753262 T 20030829; AU 2003269691 A 20030829; AU 2003271515 A 20030829; DE 10393329 T 20030829; DE 10393435 T 20030829; DE 50311172 T 20030829; EP 03750301 A 20030829; EP 03753262 A 20030829